Datasheet

FS8860

1.0A Adjustable & Fixed Voltage LDO Linear Regulator





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General Description

The FS8860 is a low-dropout linear regulator that operates in the input voltage range from +2.5V to +7.0V and delivers 1.0A output current.

The FS8860 is available in two types, fixed output voltage type or adjustable output voltage type. The fixed output voltage type is preset at an internally trimmed voltage 1.8V, 2.5V, or 3.3V. Other options 1.5V, 2.85V, 3.0V and 3.6V are available by special order only. The output voltage range of the adjustable type is from 1.25V to 5V.

The FS8860 consists of a 1.25V bandgap reference, an error amplifier, and a P-channel pass transistor. Other features include short-circuit protection and thermal shutdown protection. The FS8860 devices are available in SOT-223 and TO-252 packages.

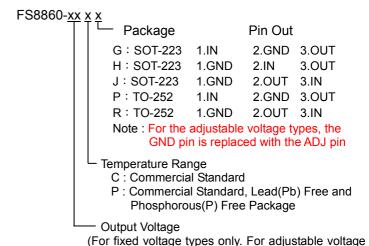
2. **Features**

- Low dropout voltage 700mV at 1.0A typ.
- · Adjustable output voltage (FS8860-Cx) or fixed output voltage (FS8860-xxCx) preset at 1.8V, 2.5V, or 3.3V
- · High output voltage accuracy
- Fixed output voltage: ±35mV
- Adjustable output voltage: ±50mV
- Small output capacitor
- · Output current limit
- · Thermal overload shutdown protection
- · SOT-223 and TO-252 Packages

Applications

- CD-ROM Drivers
- · Active SCSI Terminators
- · High Efficiency Linear Regulators
- · Monitor Microprocessors
- . Low Voltage Micro-Controllers
- · Post Regulator for Switching Power

Ordering Information



types, these two digits are eliminated.) 15:1.5V 18: 1.8V 25: 2.5V 30:3.0V

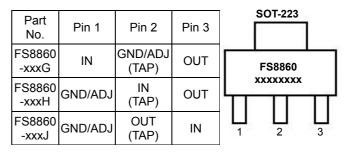
29:2.85V 36:3.6V

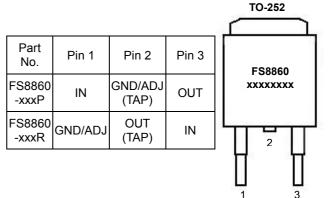
Default: Adjustable Output

Note: The output voltages other than the preset values are available by order only.

33: 3.3V

5. Pin Configurations

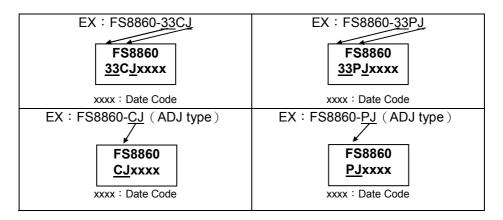




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6. Package Marking Information



7. Pin Description

Part NO.	Symbol	Description
FS8860-xxCG FS8860-xxCH	GND/ADJ	Ground pin or adjust terminal pin.
FS8860-xxCJ FS8860-xxCP	IN	Regulator input pin.
FS8860-xxCR	OUT	Regulator output pin.

IN is the regulator input pin. Supply voltage can range from 2.5V to 7.0V. An input capacitor is recommended. A 10µF tantalum on the input is a suitable input bypassing for almost all applications.

OUT is the output voltage pin. Sources up to 0.6A. Bypass with a $10\mu\text{F}$ capacitor to GND. The capacitor from VOUT to GND provides compensation feedback to the internal gain stage. This is to ensure stability at the output terminal. The minimum output capacitance is $10\mu\text{F}$ tantalum. Any increase of the output capacitance will improve the loop stability and transient response. The output capacitor increasing its value will increase stability. COUT = $100\mu\text{F}$ or more is typical for high current regulator design.

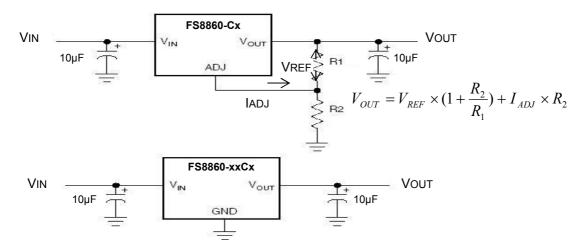
GND provides the reference for all voltages.

ADJ provides VREF=1.25V (Typ.) for adjustable output voltage.

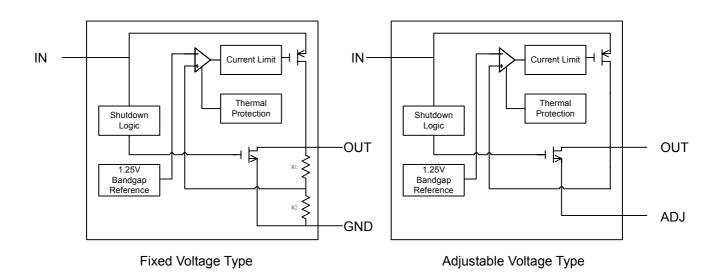
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8. Typical Application Circuit



9. Functional Block Diagrams



10. Absolute Maximum Ratings

Input voltage VIN to GND	9V
Output current limit, I(LIMIT)	1.3A
Continuous power dissipation	Internally Limited
Junction Temperature, T _J	+155°C
Storage temperature range, TSTG	55°C to +150°C
Operating junction temperature range	40°C to +125°C
Lead temperature (soldering, 10sec)	260 °C

^{*} Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and function operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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11. Electrical Characteristics

(CIN=10µF, COUT=10µF, TA=25°C , unless otherwise noted.)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Unit
VIN	Input Voltage			2.5		7.0	V
VOUT Output Voltage	Fixed Voltage Type VIN=VOUT+1.0V, IOUT=1mA		VOUT- 0.035	VOUT	VOUT+ 0.035	V	
	output voltago	Adjustable Voltage Type VIN=VOUT+1.2V, IOUT=1mA		1.20	1.25	1.30	V
Δ VOUT	Output Voltage Accuracy	VIN>VOUT+ Type)	1.0V, VIN≦7V (Fixed Voltage	-35		+35	mV
A VOOT	Output Voltage Accuracy	· VINSVOITE 2V VIN < /V (Adilistania)	+50	mV			
IMAX	Maximum Output Current			1.0			Α
ILIMIT	Current Limit					1.3	Α
ISC	Short-Circuit Current	VOUT=0V	VIN>VOUT+1.0V (Fixed Voltage Type)		050	760	V V WV MV A
130	Short-Circuit Current	VO01-0V	VIN>VOUT+1.2V (Adjustable Voltage Type)		650	760	
IQ	Ground Pin Current	ILOAD=0mA	to 1A, VIN=VOUT+1.0V		65	90	μA
IADJ	ADJ Pin Current	ILOAD=0mA	to 1A, VIN=VOUT+1.2V		65	90	μΑ
	6 11/1	IOUT=100mA			60	100	μA mV mV
VDROP	Dropout Voltage (Fixed Output Voltage	IOUT=500mA			300	500	
	Version)	IOUT=1.0A			700	1000	mV
4) /L INIT	Line Degulation	VOUT+1.0V <vin<7v, iload="1mA<br">(Fixed Voltage Type)</vin<7v,>			0.2	0.3	%/V
ΔVLINE	Line Regulation	VOUT+1.2V <vin<7v, iload="1mA<br">(Adjustable Voltage Type) IOUT=0mA to 1.0A</vin<7v,>			0.2	0.3	0 mV %/V %/V
ΔVLOAD	Load Regulation	(Fixed Voltag	је Туре)		0.02	0.03	%/mA
		IOUT=0mA to 1.0A (Adjustable Voltage Type)			0.1	0.15	%/mA
eN	Output Noise	F=1Hz to 10KHz, COUT=10µF			80		μVRMS
PSRR	Ripple Rejection	F=1KHz, CO	UT=10µF	80 μVRM:			
TSD	Thermal Shutdown Temperature				155		°C
THYS	Thermal Shutdown Hysteresis				20		°C
θЈА	Thermal Resistance (No	SOT-223			155		°C/W
33/1	heat-sink, No air flow)	TO-252		90		°C/W	

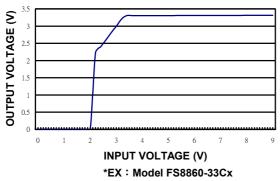
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12. Typical Operating Characteristics

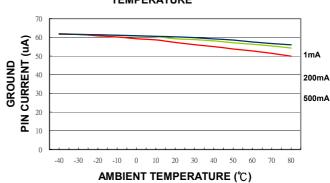
(CIN=10 μ F, COUT=10 μ F, TA=+25 $^{\circ}$ C, unless otherwise noted.)

OUTPUT VOLTAGE vs. INPUT VOLTAGE

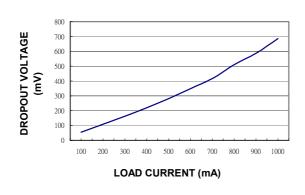


 $I_{LOAD} = 0mA$

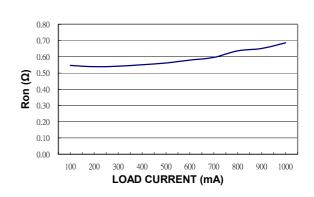
GROUND PIN CURRENT vs. AMBIENT TEMPERATURE



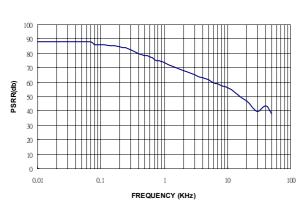
DROPOUT VOLTAGE vs. LOAD CURRENT



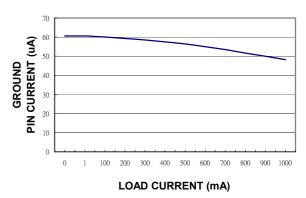
Ron vs. LOAD CURRENT



POWER SUPPLY REJECTION RATIO vs FREQUENCY

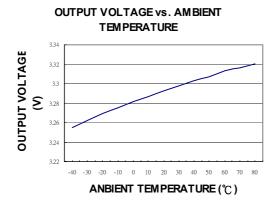


GROUND PIN CURRENT vs. LOAD CURRENT

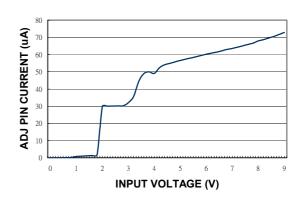


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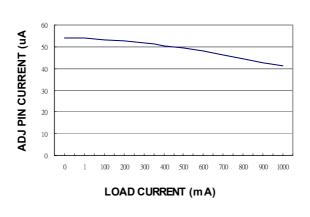




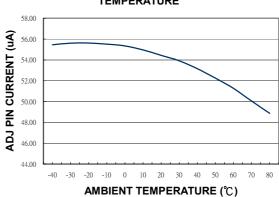
ADJ PIN CURRENT vs. INPUT VOLTAGE



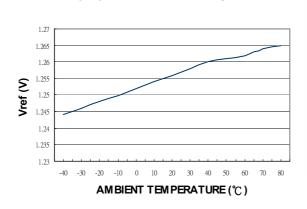
ADJ PIN CURRENT vs. LOAD CURRENT



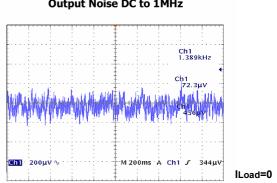




Vref vs. AMBIENT TEMPERATURE

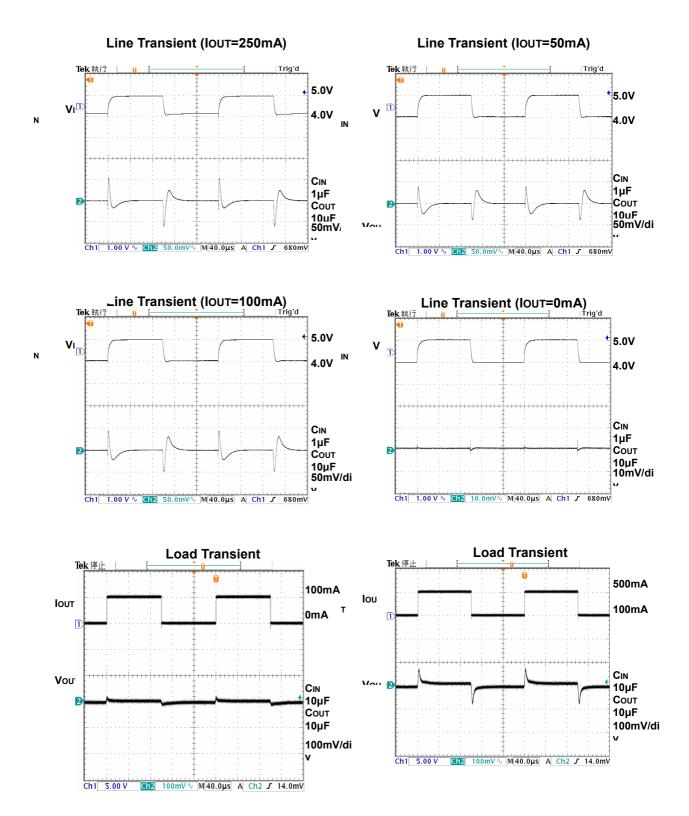


Output Noise DC to 1MHz



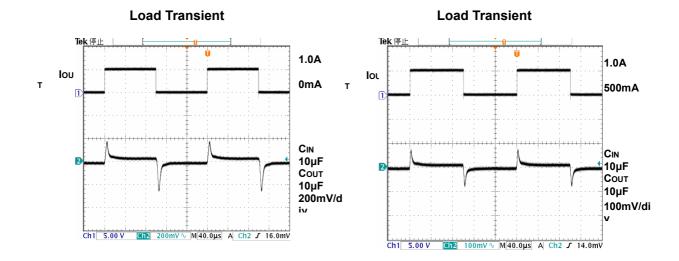
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13. Detail Description

The FS8860 is a low-dropout linear regulator. The device provides preset 1.8V, 2.5V and 3.3V output voltages for output current up to 1.0A. Adjustable output voltage and other mask options for special output voltages are also available. As illustrated in function block diagram, it consists of a 1.25V bandgap reference, an error amplifier, a P-channel pass transistor and an internal feedback voltage divider (fixed voltage types).

The 1.25V bandgap reference is connected to the error amplifier, which compares this reference with the feedback voltage and amplifies the voltage difference. If the feedback voltage is lower than the reference voltage, the pass-transistor gate is pulled lower, which allows more current to pass to the output pin and increases the output voltage. If the feedback voltage is too high, the pass-transistor gate is pulled up to decrease the output voltage.

The output voltage is feed back through an internal resistive divider (or external resistive divider for adjustable output voltage type) connected to OUT pin. Additional blocks include an output current limiter, thermal sensor, and shutdown logic.

13.1 Internal P-channel Pass Transistor

The FS8860 features a P-channel MOSFET pass transistor. Unlike similar designs using PNP pass transistors, P-channel MOSFETs require no base drive, which reduces ground pin current. PNP-based regulators also waste considerable current in dropout when the pass transistor saturates, and use high base-drive currents under large loads. The FS8860 does not suffer from these problems and consumes only 65µA (Typ.) of ground pin current under heavy loads as well as in dropout conditions.

13.2 Output Voltage Selection

For fixed voltage type of FS8860, the output voltage is preset at an internally trimmed voltage. The first two digits of part number suffix identify the output voltage (see *Ordering Information*). For example, the FS8860-33CJ has a preset 3.3V output voltage.

For adjustable voltage type of FS8860, the output

voltage is set by comparing the feedback voltage at adjust terminal to the internal bandgap reference voltage. The reference voltage VREF is 1.25V. The output voltage is given by the equation:

VOUT=VREF*(1+R2/R1)+IADJ*R2 (see *Typical Application Schematic*)

13.3 Current Limit

The FS8860 also includes a fold back current limiter. It monitors and controls the pass transistor's gate voltage, estimates the output current, and limits the output current within 1.3A.

13.4 Thermal Overload Protection

Thermal overload protection limits total power dissipation in the FS8860. When the junction temperature exceeds TJ = +155°C, a thermal sensor turns off the pass transistor, allowing the IC to cool down. The thermal sensor turns the pass transistor on again after the junction temperature cools down by 20°C, resulting in a pulsed output during continuous thermal overload conditions.

Thermal overload protection is designed to protect the FS8860 in the event of fault conditions. For continuous operation, the maximum operating junction temperature rating of TJ = +125°C should not be exceeded.

13.5 Operating Region and Power Dissipation

Maximum power dissipation of the FS8860 depends on the thermal resistance of the case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The power dissipation across the devices is $P = IOUT \times (VIN-VOUT)$. The resulting maximum power dissipation is:

$$P_{MAX} = \frac{\left(T_J - T_A\right)}{\theta_{JC} + \theta_{CA}} = \frac{\left(T_J - T_A\right)}{\theta_{JA}}$$

Where (TJ-TA) is the temperature difference

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between the FS8860 die junction and the surrounding air, θ JC is the thermal resistance of the package chosen, and θ CA is the thermal resistance through the printed circuit board, copper traces and other materials to the surrounding air. For better heat-sinking, the copper area should be equally shared between the IN, OUT, and GND pins.

If the FS8860 uses a SOT-223 package and this package is mounted on a double sided printed circuit board with two square inches of copper allocated for "heat spreading", the resulting θ JA is 80 °C/W.

Based on the maximum operating junction temperature 125 °C with an ambient of 25°C, the maximum power dissipation will be:

$$P_{MAX} = \frac{(T_J - T_A)}{\theta_{JC} + \theta_{CA}} = \frac{(125 - 25)}{80} = 1.25W$$

Thermal characteristics were measured using a double-sided board with 1" x 2" square inches of copper area connected to the GND pin for "heat spreading".

13.6 Input-Output Voltage

A regulator's minimum input-output voltage differential, or dropout voltage, determines the lowest usable supply voltage. In battery-powered systems, this will determine the useful end-of-life battery voltage. The FS8860 uses a P-channel MOSFET pass transistor, its dropout voltage is a function of drain-to-source on-resistance (RDS(ON)) multiplied by the output current.

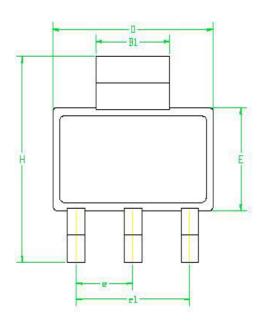
VDROPOUT = VIN-VOUT = RDS(ON) x IOUT

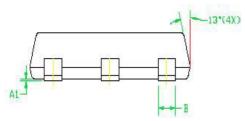
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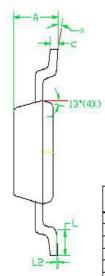


14. Package Outline

14.1 SOT-223





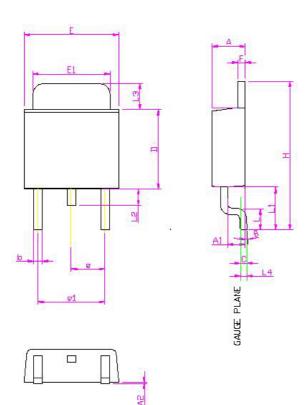


	MILLIMET	TERS	INCHES			
SAMBOLS	MIN	NAX	MIN	MAX		
Α	1.55	190	0.061	0.071		
A1	0.02	0.12	0.000B	0.0047		
В	0.60	08:0	0.024	0.031		
B1	2.90	3.10	0.114	0.122		
_	0.24	SEO	0.009	0.013		
П	6.30	6.7D	0.248	D.264		
Ē	3.30	3.70	0.130	0.146		
	2.30	2.30 BSC		0.090 020		
el	4.60	BSC	0.181 BSC			
Н	6.70	7.30	0.264	0.287		
Ľ	0.90 MIN		NIM 9E0.0			
Le	1.06 BSC		D.00248SC			
α	0,	10*	Do	10"		

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14.2 TO-252



D.	MILLIF	MILLIMETERS		INCHES		
1	MIN.	MAX.	MIN.	MAX.		
A	2.19	2.38	0.086	0.094		
A1	0.89	1.27	0.035	0.050		
A2	0.00	0.13	00.0	0.005		
ь	0.51	0.89	0.02	0.035		
C	0.46	0.58	0.018	0.023		
D	5.97	6.22	0.235	0.245		
E	6.35	6.73	0.250	0.265		
E1	5.21	5.46	0.205	0.215		
e	2.28 BSC		0.090 BSC			
e1	3.96	5.18	0.156	0.204		
F	0.46	0.58	0.018	0.023		
L	1.40	1.78	0.055	0.070		
L1	2.67(REF.)		0.105(REF.)		
L2	0.64	1.02	0.025	0.040		
L3	1.52	2.03	0.060	0.080		
L4	0.51 BSC		0.020	BSC		
н	9.40	10.4	0.370	0.410		
G-	0.	8"	0,	8.		

Note: 1. Package body sizes exclude mold flash protrusions or gate burrs.
 2. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.
 3. Followed from JEDEC TO-252

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